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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/685,910	10/15/2003	Yong-Chan Keh	5000-1-443	6253	
33942	7590 12/09/2005		EXAMINER		
CHA & REI	•	NGUYEN, TUAN N			
PARAMUS,	4 EAST STE 103 NJ 07652	ART UNIT	PAPER NUMBER		
,			2828	- · · · - · · · · · · · · · · · · · · ·	
			DATE MAILED: 12/09/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary		Applicati	on No.	Applicant(s)	
		10/685,9	10	KEH ET AL.	(PM)
		Examine		Art Unit	
		Tuan N. N		2828	
Period fo	- The MAILING DATE of this communication Reply	on appears on th	e cover sheet with the	correspondence add	ress
WHIC - Exten after: - If NO - Failur Any re	DRTENED STATUTORY PERIOD FOR F HEVER IS LONGER, FROM THE MAILII sions of time may be available under the provisions of 37 (SIX (6) MONTHS from the mailing date of this communicat period for reply is specified above, the maximum statutory e to reply within the set or extended period for reply will, by eply received by the Office later than three months after the d patent term adjustment. See 37 CFR 1.704(b).	NG DATE OF TI CFR 1.136(a). In no evition. period will apply and w y statute, cause the app	HIS COMMUNICATIO ent, however, may a reply be ti rill expire SIX (6) MONTHS fror olication to become ABANDON	N. mely filed n the mailing date of this con ED (35 U.S.C. § 133).	
Status					
2a)☐ 3)☐	Responsive to communication(s) filed on This action is FINAL . 2b) Since this application is in condition for a closed in accordance with the practice ur	This action is reliable to the second the se	for formal matters, pr		merits is
Dispositi	on of Claims				
5)⊠ 6)⊠ 7)⊠ 8)□ Applicati 9)□ -	Claim(s) 1-21 is/are pending in the application of the above claim(s) is/are with Claim(s) 15-21 is/are allowed. Claim(s) 1-3,5-8 and 10-14 is/are rejected to. Claim(s) 4 and 9 is/are objected to. Claim(s) are subject to restriction is con Papers The specification is objected to by the Example of the drawing(s) filed on is/are: a) Applicant may not request that any objection is Replacement drawing sheet(s) including the of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to by the contraction of the oath or declaration is objected to be the oath of the oath or declaration is objected to be the oath of the oath oath oath oath oath oath oath oath	ithdrawn from code. and/or election remainer. accepted or by to the drawing(s) correction is require	equirement. Objected to by the perheld in abeyance. Seried if the drawing(s) is of	ee 37 CFR 1.85(a). Djected to. See 37 CFF	` '
Priority u	nder 35 U.S.C. § 119				
12)⊠ / a)[Acknowledgment is made of a claim for for All b) Some * c) None of: 1. Certified copies of the priority docu 2. Certified copies of the priority docu 3. Copies of the certified copies of the application from the International Beet he attached detailed Office action for	uments have bee uments have bee e priority docum Bureau (PCT Rul	en received. en received in Applicat ents have been receiv e 17.2(a)).	tion No red in this National S	stage
2) 🔲 Notice 3) 🔲 Inform	(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-94 nation Disclosure Statement(s) (PTO-1449 or PTO/5 No(s)/Mail Date		4) Interview Summan Paper No(s)/Mail D 5) Notice of Informal I 6) Other:	oate	152)

1. The following is a quotation of 35 U.S.C. 102(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

2. Claims 1, 7, 10 are rejected under 35 U.S.C. 102(a) as being unpatentable over Yagi et al.

(US 6868105).

With respect to claims 1, 10 Yagi et al. '105 shows and discloses an optical element module package (Fig 16) having a laser diode (Fig 6: 5 LD) for projecting optical signals and a photo diode (Fig 6: 6 photodiode)(Col 15: 25-67) for monitoring the optical signals projected from the laser diode, comprising: a stem (Col 1: 40-45) having a first through-hole formed in a long-hole shape that is parallel to the diametrical direction of the stem (ABSTRACT) (Fig 1a, 1c: surface through hole 1a, 1b along or parallel to the stem to be connected to the optical elements 4-7); and a plurality of leads arranged in a row (Fig 1a: 2g-2l plural through leads) and provided in the first through-hole, wherein the first through-hole is filled with a sealant of a glass material (Col 2: 15-20, seal the hole with glass process that suitable for mass production) so that the stem and the plurality of leads are held together. Since claim 10 recites the same or identical elements/limitations it is inherent to use patents ('105) to recite the method of manufacturing an optical element module package, product by process.

With respect to claim 7, Yagi et al. '105 shows and discloses the package further comprises a pair of second through-holes extending through the stem from one side to the other and a pair of additional leads extending through the second through-holes (Fig 1a: 2a-2f second

through hole, 2g-2l first through hole, 1a, 6-7, wire leads through the stem casing to the other side connecting to LD, and photodetector), wherein the second through-holes are filled with a sealant of a glass material so that the stem and the additional leads are held together (Col 1: 40-46) (Col 2: 15-25 seal hole with glass).

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

- 1. Determining the scope and contents of the prior art.
- 2. Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- 4. Considering objective evidence present in the application indicating obviousness or non-obviousness.
- 4. Claims 2-3, 5-6, 8, 11-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yagi et al. (US 6868105) in view of Applicant's Prior Art (Fig 1,2).

With respect to claims 2, 11 the claim further require the stem has a heat sink block protruding from one end thereof, the heat sink block being adjacent to the first through-hole. Yagi et al. '105 discloses the above, however did not discreetly disclose about the heat sink adjacent to next through-hole. Applicant Prior Art (Fig 2) shows a laser device having heat sink

block (Fig 2: 211) protruding from one end and adjacent to the first through hole (Fig 2: through hole formed from ceramic feed through and stem). It would have been obvious to one of ordinary skill in the art to provide Yagi et al. '105 with the heat sink as taught or suggested by Applicant Prior Art (Fig 2), for the benefit of aligning the laser light to reduce heat generate within the device to extend the life of the laser device.

With respect to claims 3, 12 Applicant's Prior Art (Fig 1,2) shows a sub-mount attached to one end of the heat sink block (Fig 2: laser block on top of the sub-mount "not label or number" on top of the heat sink". Yagi et al. '105 further shows the sub-mount (Col 2: 21-25) (Col 4: 27-30 sub-mount) having a circuit pattern formed on a surface thereof (Fig 4, 5: 8 sub-mount with circuit wiring - the lead wires inherently need to be connected to the laser diode, photodiode, and other elements, now has been formed on the sub-mount to reduce clutter).

With respect to claims 5,6 Applicant's Prior Art (Fig 1: 102, 103, 104) shows and discloses the plurality of leads includes a DC bias lead for the laser diode, a radio-frequency signal lead, a lead for the monitoring photo diode, and at least one ground lead (Col 1: section [0006-0007] electrical RF signal, DC bias, cathode lead, diode, and corresponding leads).

With respect to claim 8, the claim further require a pair of additional leads is a DC bias lead for the laser diode and the other is a lead for the monitoring photo diode. Applicant's Prior Art (Fig 1) (Col 1: section [0006] disclose DC bias lead to laser diode 103 and photodiode 104).

With respect to claims 13, 14 the claims further require a step of sealing through-hole, wherein the sealant is melted at a temperature of about 500.degree. C. Yagi et al. '105 did not discretely disclose the range of temperature around 500 degree C, however Yagi et al. '105 did shows and discloses the lead have been aligned and fixed where sealing is heat to bond the elements together (Col 4: 13-45; Fig 1), and Applicant's Prior Art (Fig 1) (Col 1: section [0007]) further discloses the use of heat to bond the leads together with the stem. It has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or workable range involves only routine skill in the art, in this case is the range of melting the resin or glass to bond to the semiconductor and wiring. In re Aller, 105 USPQ 233.

REASON FOR ALLOWANCE

Allowable Subject Matter

5. The following is an examiner's statement of reasons for allowance - Applicant's response filed on 10/15/2003 has been considered, with respect to claim 15 the references of the record fail to teach or suggest:

Claim 15:

An optical element module package having a laser diode for projecting optical signals and a photo diode for monitoring the optical signals projected from the laser diode, comprising: a stem having a first through-hole formed in a long-hole shape and a pair of second through-holes formed on the stem; and a radio-frequency lead provided in the first through-hole and a plurality of leads provided in the second through-holes.

Application/Control Number: 10/685,910 Page 6

Art Unit: 2828

6. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Allowable Subject Matter

7. Claims 4, 9 objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The references of the record fail to teach or suggest:

Claim 4:

An optical module package having a laser diode, photodiode comprising a stem and wires formed in a long first through hole sealed with glass material, with a laser diode mounted on a sub-mount having a circuit form on the surface, where the stem has a heat sink block adjacent to the first through hole.

Claim 9:

The package further comprises a second through-holes extending through the stem and sealed with glass material, wherein the stem has a heat sink block protruding from one end and positioned between the second through-holes adjacent to the first through-hole.

Communication Information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan N Nguyen whose telephone number is (571) 272-1948. The examiner can normally be reached on M-F: 7:30 - 4:30PM.

Application/Control Number: 10/685,910

Art Unit: 2828

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Harvey Minsun can be reached on (571) 272-1835. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tuan N. Nguyen

Tuan Ngyn

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Page 7